

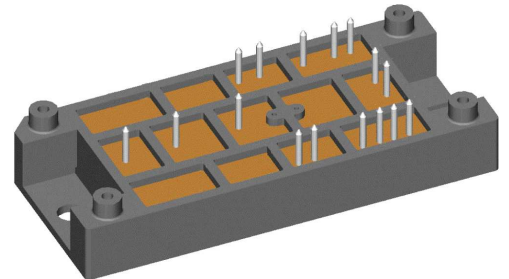
Standard Rectifier Module

3~ Rectifier	Brake Chopper
$V_{RRM} = 1600 \text{ V}$	$V_{CES} = 1200 \text{ V}$
$I_{DAV} = 180 \text{ A}$	$I_{C25} = 250 \text{ A}$
$I_{FSM} = 1100 \text{ A}$	$V_{CE(sat)} = 1.7 \text{ V}$

3~ Rectifier Bridge + Brake Unit + NTC

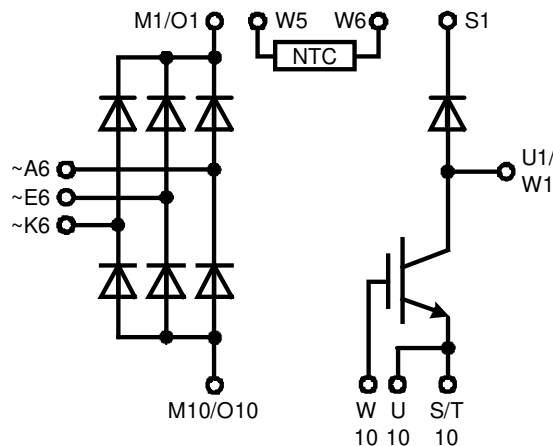
Part number

VUB160-16NOXT



Backside: isolated

 E72873



Features / Advantages:

- Package with DCB ceramic base plate
- Improved temperature and power cycling
- Planar passivated chips
- Very low forward voltage drop
- Very low leakage current
- X2PT - 2nd generation Xtreme light Punch Through
- Rugged X2PT design results in:
 - short circuit rated for 10 μsec .
 - very low gate charge
 - low EMI
 - square RBSOA @ 2x I_c
- Thin wafer technology combined with X2PT design results in a competitive low $V_{CE(sat)}$ and low thermal resistance

Applications:

- 3~ Rectifier with brake unit for drive inverters

Package: V2-Pack

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Height: 17 mm
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

Disclaimer Notice

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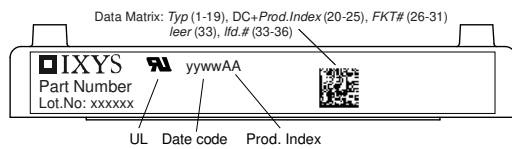
Rectifier				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{RSM}	max. non-repetitive reverse blocking voltage					1700	V
V_{RRM}	max. repetitive reverse blocking voltage					1600	V
I_R	reverse current	$V_R = 1600$ V	$T_{VJ} = 25^\circ\text{C}$			100	μA
		$V_R = 1600$ V	$T_{VJ} = 125^\circ\text{C}$			2	mA
V_F	forward voltage drop	$I_F = 60$ A	$T_{VJ} = 25^\circ\text{C}$			1.16	V
		$I_F = 180$ A				1.55	V
		$I_F = 60$ A	$T_{VJ} = 125^\circ\text{C}$			1.09	V
		$I_F = 180$ A				1.59	V
I_{DAV}	bridge output current	$T_C = 90^\circ\text{C}$ rectangular	$T_{VJ} = 150^\circ\text{C}$ $d = \frac{1}{3}$			180	A
V_{FO}	threshold voltage	} for power loss calculation only				0.81	V
r_F	slope resistance					4.4	m Ω
R_{thJC}	thermal resistance junction to case					0.6	K/W
R_{thCH}	thermal resistance case to heatsink				0.2		K/W
P_{tot}	total power dissipation			$T_C = 25^\circ\text{C}$		205	W
I_{FSM}	max. forward surge current	$t = 10$ ms; (50 Hz), sine	$T_{VJ} = 45^\circ\text{C}$			1.10	kA
		$t = 8,3$ ms; (60 Hz), sine	$V_R = 0$ V			1.19	kA
		$t = 10$ ms; (50 Hz), sine	$T_{VJ} = 150^\circ\text{C}$			935	A
		$t = 8,3$ ms; (60 Hz), sine	$V_R = 0$ V			1.01	kA
I^2t	value for fusing	$t = 10$ ms; (50 Hz), sine	$T_{VJ} = 45^\circ\text{C}$			6.05	kA ² s
		$t = 8,3$ ms; (60 Hz), sine	$V_R = 0$ V			5.89	kA ² s
		$t = 10$ ms; (50 Hz), sine	$T_{VJ} = 150^\circ\text{C}$			4.37	kA ² s
		$t = 8,3$ ms; (60 Hz), sine	$V_R = 0$ V			4.25	kA ² s
C_J	junction capacitance	$V_R = 400$ V; $f = 1$ MHz	$T_{VJ} = 25^\circ\text{C}$		37		pF



Brake IGBT + Diode				Ratings					
Symbol	Definition	Conditions	min.	typ.	max.	Unit			
V_{CES}	collector emitter voltage	$T_{VJ} = 25^{\circ}C$			1200	V			
V_{GES}	max. DC gate voltage				± 20	V			
V_{GEM}	max. transient gate emitter voltage				± 30	V			
I_{C25}	collector current	$T_C = 25^{\circ}C$			250	A			
I_{C80}		$T_C = 80^{\circ}C$			175	A			
P_{tot}	total power dissipation	$T_C = 25^{\circ}C$			695	W			
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 150\text{ A}; V_{GE} = 15\text{ V}$			1.7	V			
					1.9	V			
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 6\text{ mA}; V_{GE} = V_{CE}$	6	6.8	7.5	V			
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0\text{ V}$			0.1	mA			
					0.1	mA			
I_{GES}	gate emitter leakage current	$V_{GE} = \pm 20\text{ V}$			500	nA			
$Q_{G(on)}$	total gate charge	$V_{CE} = 600\text{ V}; V_{GE} = 15\text{ V}; I_C = 150\text{ A}$		510		nC			
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 600\text{ V}; I_C = 150\text{ A}$ $V_{GE} = \pm 15\text{ V}; R_G = 1.2\ \Omega$							
t_r	current rise time						$T_{VJ} = 125^{\circ}C$	220	ns
$t_{d(off)}$	turn-off delay time						100	ns	
t_f	current fall time						400	ns	
E_{on}	turn-on energy per pulse						220	ns	
E_{off}	turn-off energy per pulse						21.5	mJ	
		17	mJ						
RBSOA	reverse bias safe operating area	$V_{GE} = \pm 15\text{ V}; R_G = 1.2\ \Omega$							
I_{CM}		$V_{CEK} = 1200\text{ V}$			450	A			
SCSOA	short circuit safe operating area	$V_{CEK} = 1200\text{ V}$							
t_{SC}	short circuit duration	$V_{CE} = 900\text{ V}; V_{GE} = \pm 15$			10	μs			
I_{SC}	short circuit current	$R_G = 1.2\ \Omega$; non-repetitive			650	A			
R_{thJC}	thermal resistance junction to case				0.16	K/W			
R_{thCH}	thermal resistance case to heatsink				0.10	K/W			
Brake Diode									
V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25^{\circ}C$			1200	V			
I_{F25}	forward current	$T_C = 25^{\circ}C$			48	A			
I_{F80}		$T_C = 80^{\circ}C$			32	A			
V_F	forward voltage	$I_F = 30\text{ A}$			2.75	V			
					1.60	V			
I_R	reverse current	$V_R = V_{RRM}$			0.25	mA			
					1	mA			
Q_{rr}	reverse recovery charge	$V_R = 600\text{ V}$ $-di_f/dt = 900\text{ A}/\mu s$ $I_F = 30\text{ A}; V_{GE} = 0\text{ V}$							
I_{RM}	max. reverse recovery current						$T_{VJ} = 125^{\circ}C$	6	μC
t_{rr}	reverse recovery time						50	A	
E_{rec}	reverse recovery energy						350	ns	
					2	mJ			
R_{thJC}	thermal resistance junction to case				0.9	K/W			
R_{thCH}	thermal resistance case to heatsink				0.3	K/W			



Package V2-Pack		Ratings				
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			100	A
T_{VJ}	virtual junction temperature		-40		150	°C
T_{op}	operation temperature		-40		125	°C
T_{stg}	storage temperature		-40		125	°C
Weight				76		g
M_D	mounting torque		2		2.5	Nm
$d_{Spp/App}$	creepage distance on surface / striking distance through air	terminal to terminal	6.0			mm
$d_{Spb/Apb}$		terminal to backside	12.0			mm
V_{ISOL}	isolation voltage	t = 1 second 50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA	3600			V
		t = 1 minute	3000			V



Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	VUB160-16NOXT	VUB160-16NOXT	Box	6	521692

Similar Part	Package	Voltage class
VUB160-16NOX	V2-Pack	1600

Temperature Sensor NTC

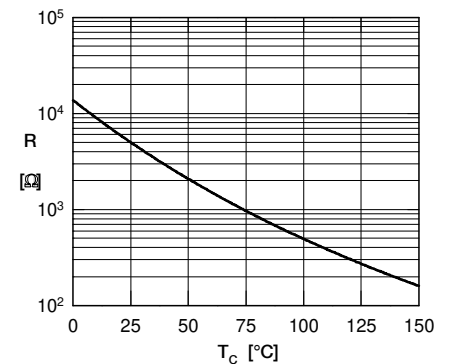
Symbol	Definition	Conditions	min.	typ.	max.	Unit
R_{25}	resistance	$T_{VJ} = 25^\circ$	4.75	5	5.25	k Ω
$B_{25/50}$	temperature coefficient			3375		K

Equivalent Circuits for Simulation

* on die level

$T_{VJ} = 150^\circ\text{C}$

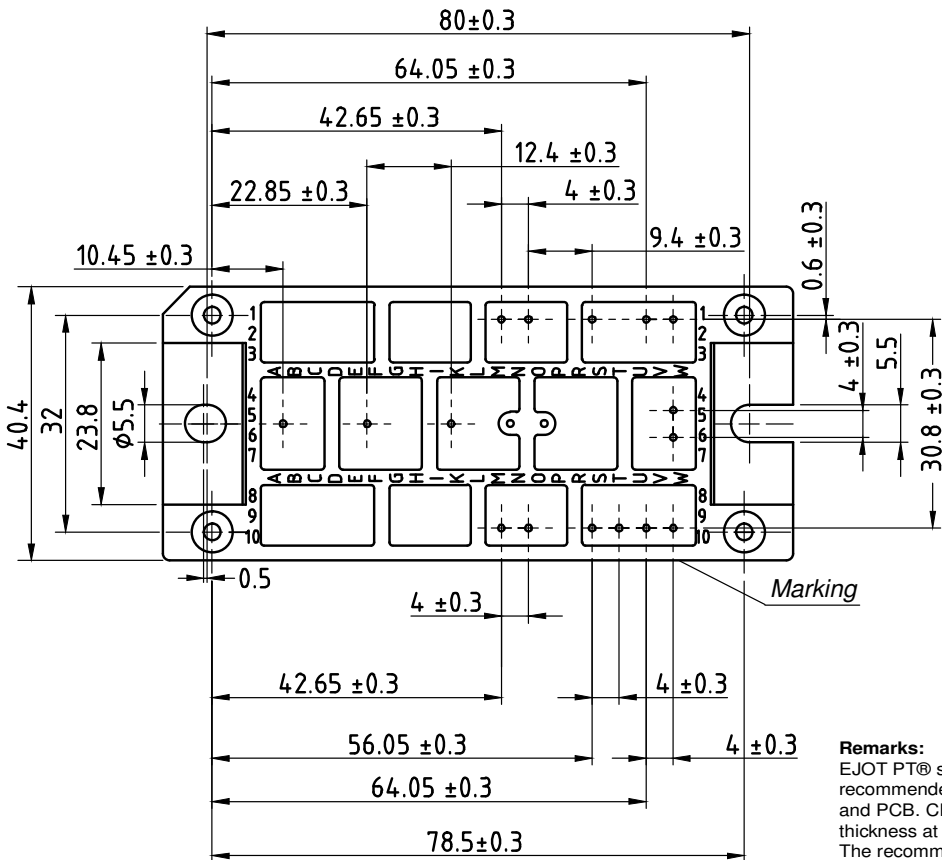
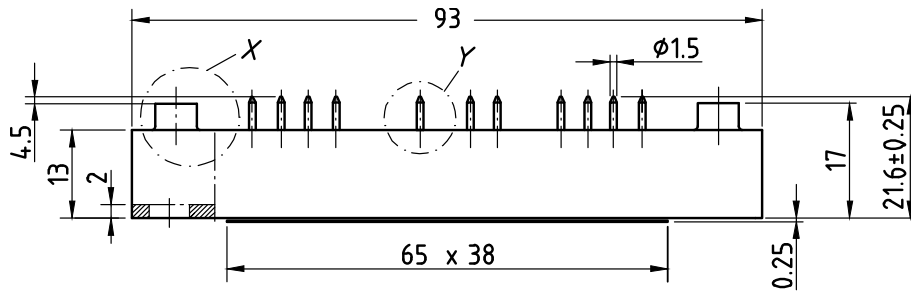
	Rectifier	Brake IGBT +	Brake Diode	
$V_{0\max}$	threshold voltage	0.81	1.1	1.31 V
$R_{0\max}$	slope resistance *	3.2	13.8	8 m Ω



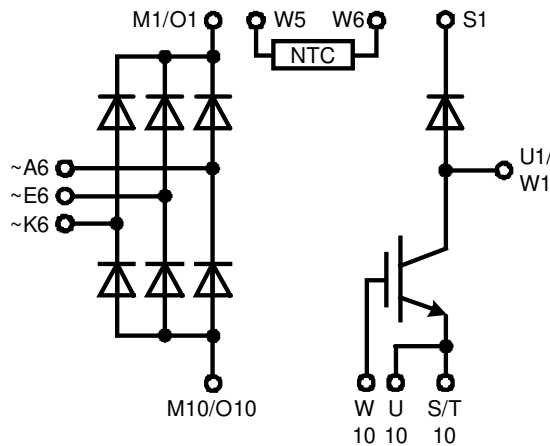
Typ. NTC resistance vs. temperature



Outlines V2-Pack



Remarks:
EJOT PT® self-tapping screws of the dimension K25 are recommended for the mechanical connection between module and PCB. Choose the right length according to your board thickness at a maximum depth of 6 mm of the module holes. ^L
The recommended mounting torque is 1.5 Nm.



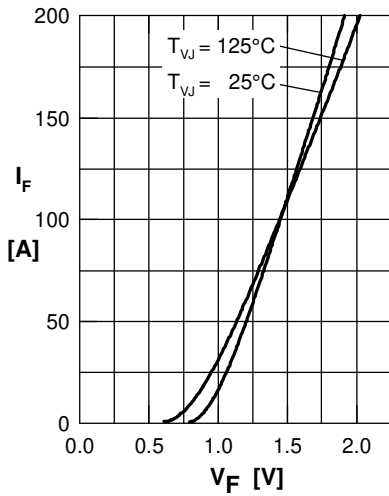
Rectifier


Fig. 1 Forward current vs. voltage drop per diode

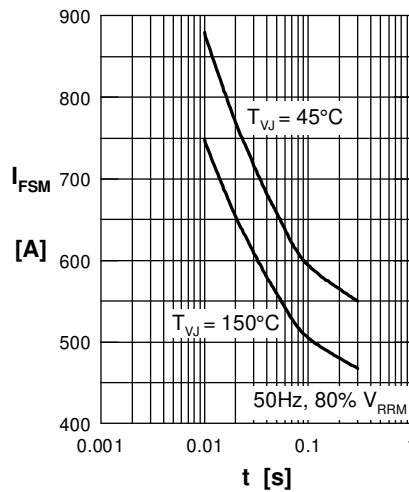


Fig. 2 Surge overload current vs. time per diode

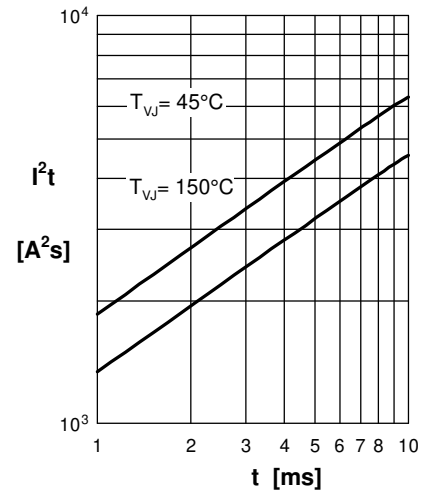
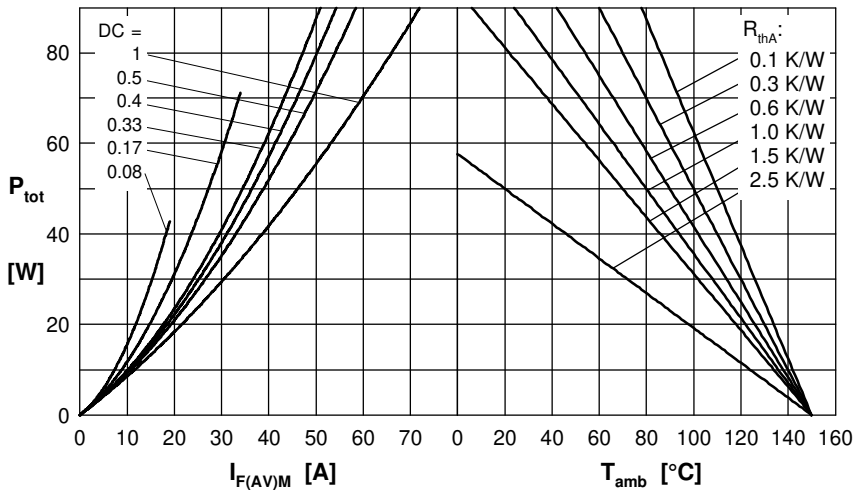

 Fig. 3 I^2t vs. time per diode


Fig. 4 Power dissipation vs. forward current and ambient temperature per diode

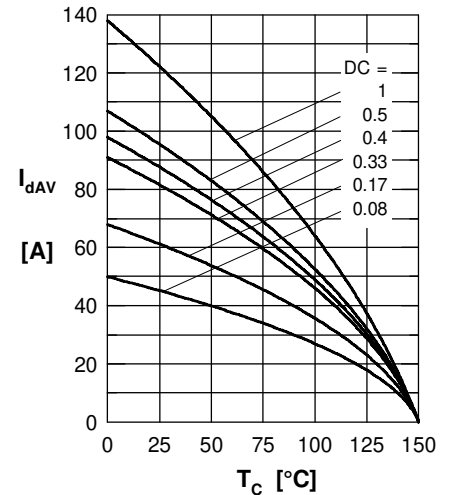


Fig. 5 Max. forward current vs. case temperature per diode

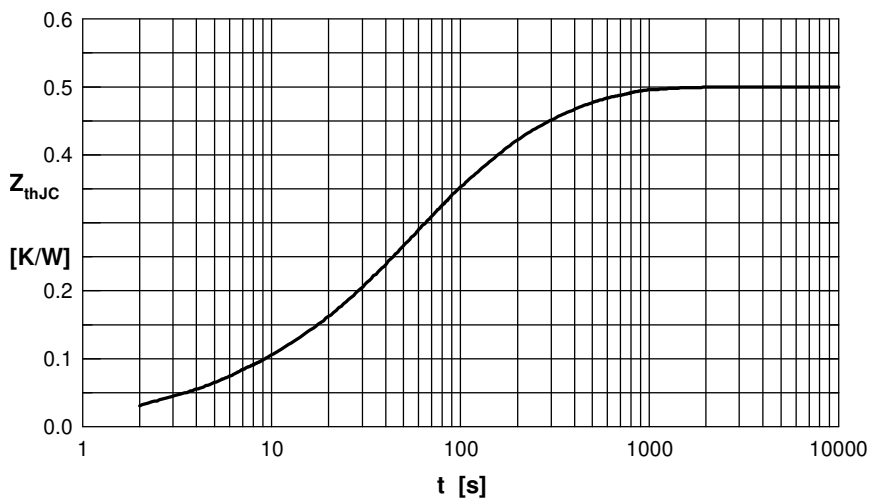


Fig. 6 Transient thermal impedance junction to case vs. time per diode

 Constants for Z_{thJC} calculation:

i	R_{th} (K/W)	t_i (s)
1	0.040	0.004
2	0.003	0.010
3	0.140	0.030
4	0.120	0.300
5	0.197	0.080

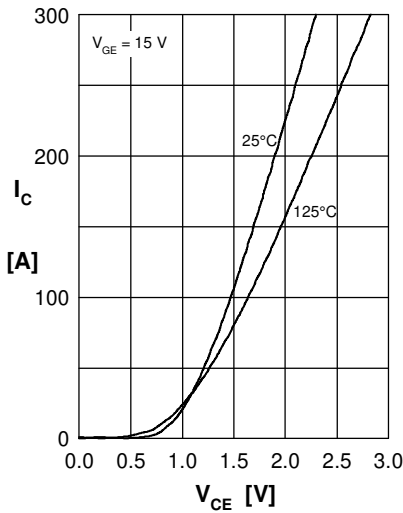
Brake IGBT + Diode


Fig.1 Output characteristics IGBT

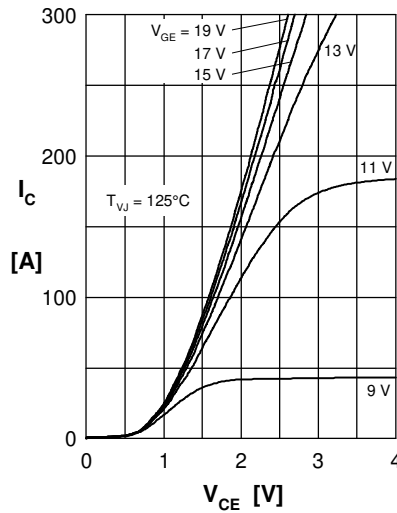


Fig.2 Typ. output characteristics IGBT

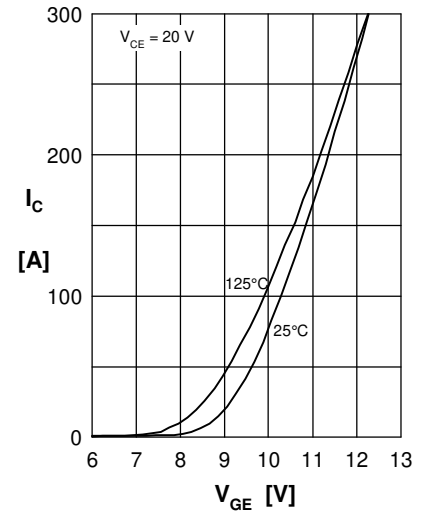


Fig.3 Typ. transfer charact. IGBT

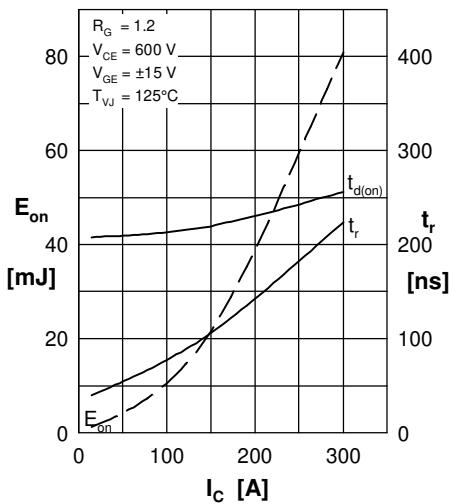


Fig.4 Typ. turn-on energy & switch. times vs. collector current

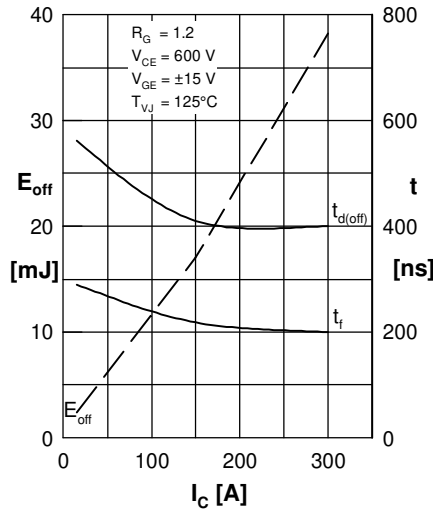


Fig.5 Typ. turn-off energy & switch. times vs. collector current

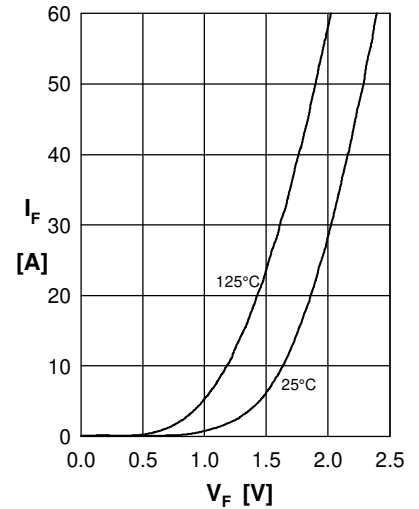


Fig.6 Typ. forward characteristics Diode

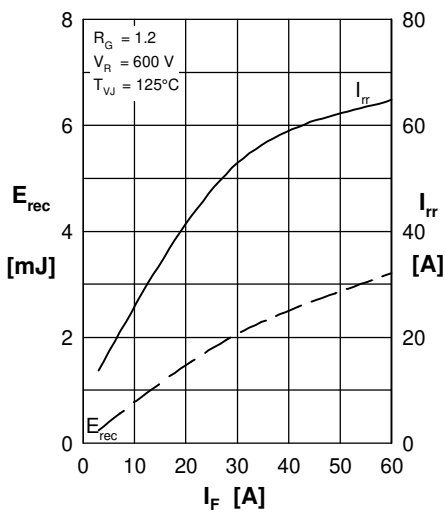


Fig.7 Typ. reverse recovery characteristics Diode

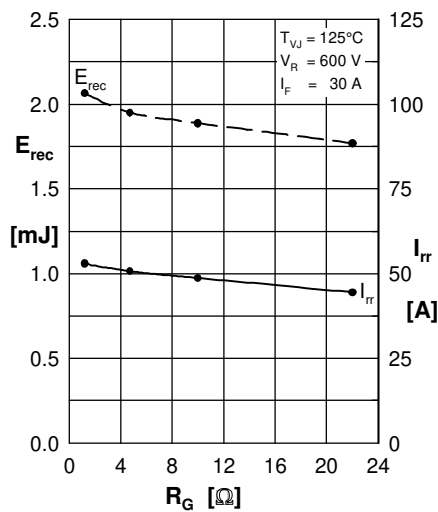


Fig.8 Typ. reverse recovery characteristics Diode

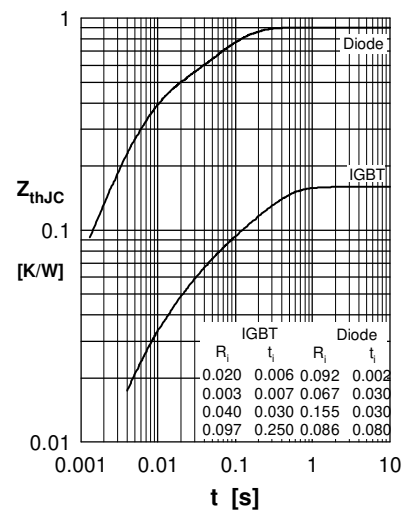


Fig.9 Transient thermal resistance junction to case